2SC3512

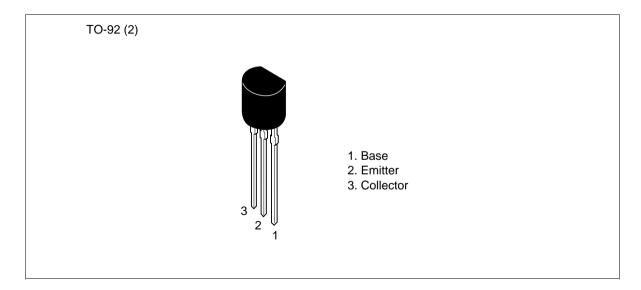
Silicon NPN Epitaxial

HITACHI

Application

UHF / VHF wide band amplifier

Outline





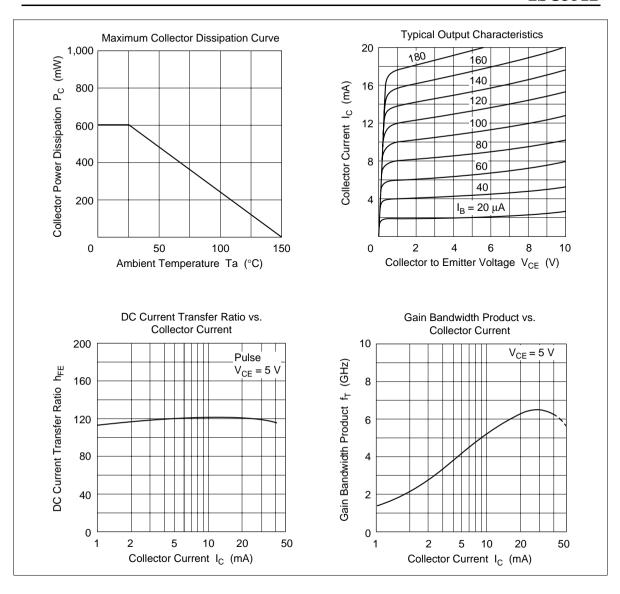
2SC3512

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

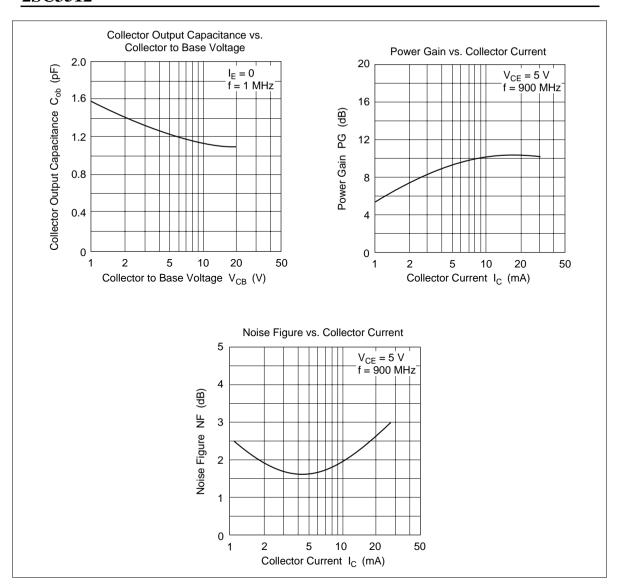
| Item | Symbol | Ratings | Unit |
|------------------------------|------------------|-------------|------|
| Collector to base voltage | V_{CBO} | 15 | V |
| Collector to emitter voltage | V_{CEO} | 11 | V |
| Emitter to base voltage | V_{EBO} | 2 | V |
| Collector current | I _c | 50 | mA |
| Collector power dissipation | P _c | 600 | mW |
| Junction temperature | Tj | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

Electrical Characteristics (Ta = 25°C)

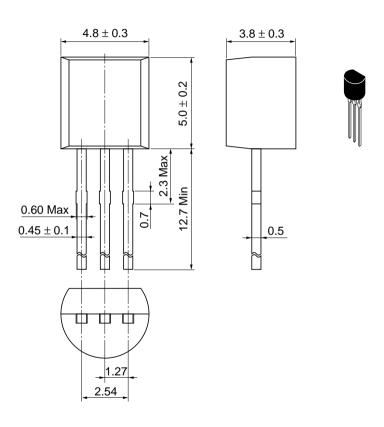
| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
|-------------------------------------|------------------|-----|------|-----|------|---|
| Collector to base breakdown voltage | $V_{(BR)CBO}$ | 15 | _ | _ | V | $I_{c} = 10 \ \mu A, \ I_{E} = 0$ |
| Collector to cutoff current | I _{CEO} | _ | _ | 1 | μΑ | V _{CE} = 10 V, R _{BE} = ∞ |
| Emitter cutoff current | I _{EBO} | _ | _ | 1 | μΑ | V _{EB} = 1 V, I _C = 0 |
| Collector cutoff current | I _{CBO} | _ | _ | 1 | μΑ | V _{CB} = 12 V, I _E = 0 |
| DC current transfer ratio | h _{FE} | 50 | 120 | 250 | | $V_{CE} = 5 \text{ V}, I_{C} = 20 \text{ mA}$ |
| Collector output capacitance | Cob | _ | 1.2 | 1.6 | pF | $V_{CB} = 5 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$ |
| Gain bandwidth product | f _T | _ | 6.0 | _ | GHz | $V_{CE} = 5 \text{ V}, I_{C} = 20 \text{ mA}$ |
| Power gain | PG | _ | 10.5 | _ | dB | $V_{CE} = 5 \text{ V}, I_{C} = 20 \text{ mA},$ f = 900 MHz |
| Noise figure | NF | _ | 1.6 | _ | dB | $V_{CE} = 5 \text{ V}, I_{C} = 5 \text{ mA},$ f = 900 MHz |



2SC3512



Unit: mm



| Hitachi Code | TO-92 (2) |
|--------------------------|-----------|
| JEDEC | Conforms |
| EIAJ | Conforms |
| Weight (reference value) | 0.25 g |

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